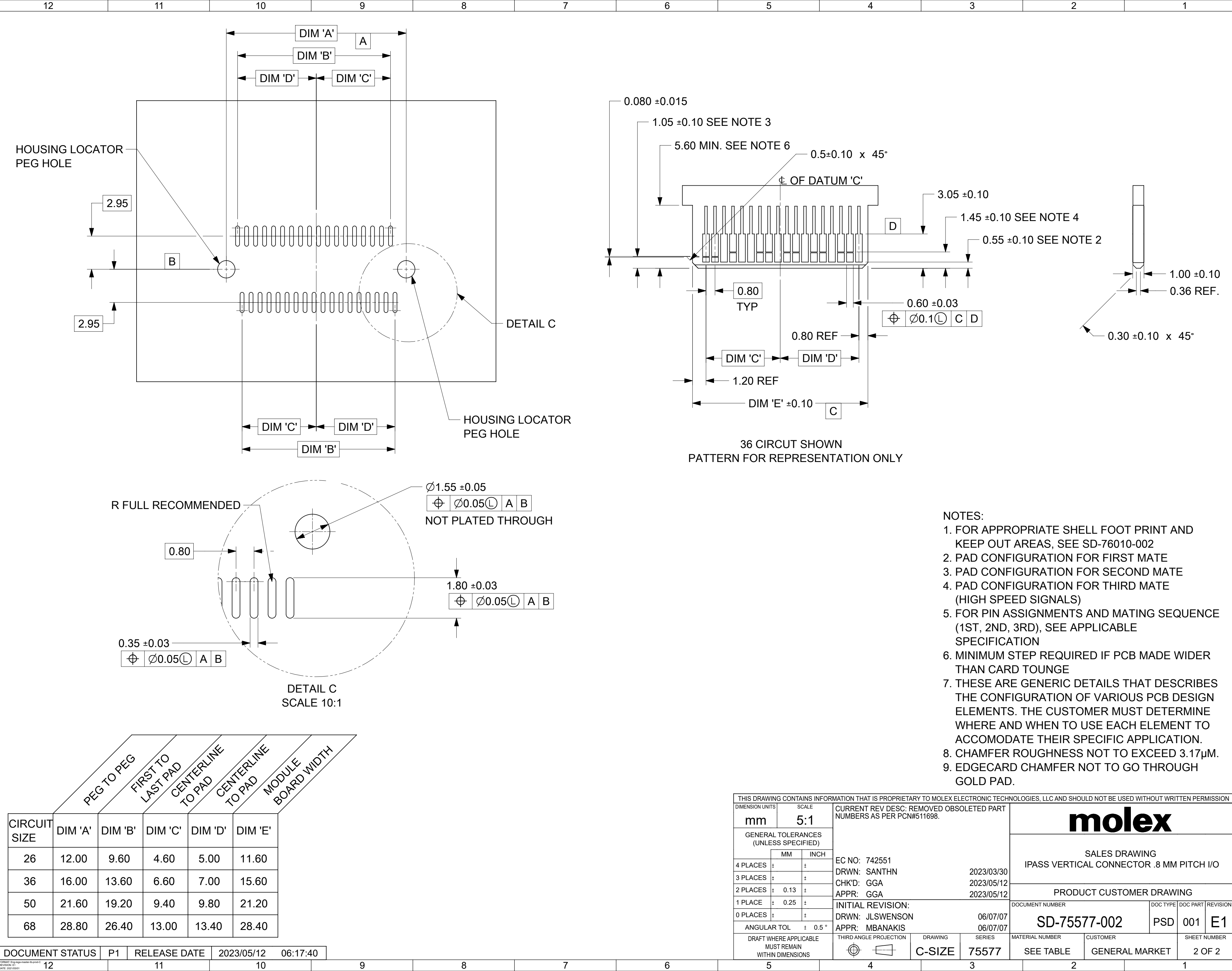




	PEG TO PEG	FIRST TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH
CIRCUIT SIZE	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'
26	12.00	9.60	4.60	5.00	11.60
36	16.00	13.60	6.60	7.00	15.60
50	21.60	19.20	9.40	9.80	21.20
68	28.80	26.40	13.00	13.40	28.40

DOCUMENT STATUS	P1	RELEASE DATE	2023/05/12	06:17:40
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THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										
DIMENSION UNITS		SCALE		CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#511698.			molex			
mm		5:1								
GENERAL TOLERANCES (UNLESS SPECIFIED)										
	MM	INCH	EC NO: 742551 DRWN: SANTHN 2023/03/30 CHK'D: GGA 2023/05/12 APPR: GGA 2023/05/12			SALES DRAWING IPASS VERTICAL CONNECTOR .8 MM PITCH I/O				
4 PLACES	±	±								
3 PLACES	±	±								
2 PLACES	± 0.13	±								
1 PLACE	± 0.25	±								
0 PLACES	±	±	INITIAL REVISION: DRWN: JLSWENSON 06/07/07 APPR: MBANAKIS 06/07/07			PRODUCT CUSTOMER DRAWING				
ANGULAR TOL		± 0.5 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
						SD-75577-002		PSD	001	E1
			THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER	CUSTOMER		SHEET NUMBER	
				C-SIZE	75577	SEE TABLE	GENERAL MARKET		2 OF 2	